

Title (en)
HEAT SINK

Title (de)
KÜHLKÖRPER

Title (fr)
DRAIN THERMIQUE

Publication
EP 1374654 A1 20040102 (EN)

Application
EP 02753633 A 20020314

Priority
• GB 0106547 A 20010316
• US 0207904 W 20020314
• US 93935601 A 20010824

Abstract (en)
[origin: WO02076166A1] A composite heat sink device (1) includes a heat sink body (2, 3) formed of aluminum, the body (2, 3) having a pair of coplanar surfaces (4), and a thermally conductive solderable element (5), for example of copper, mechanically fixed to each of the coplanar surfaces (4). Each of the solderable elements has a first surface which is contiguous with one of the coplanar surfaces, and a second surface which is soldered to a printed circuit board.

IPC 1-7
H05K 7/20; **H01L 23/367**; **H01L 23/40**

IPC 8 full level
H05K 7/20 (2006.01); **H01L 23/36** (2006.01); **H01L 23/367** (2006.01); **H01L 23/40** (2006.01); **H05K 3/34** (2006.01)

CPC (source: EP)
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C-Set (source: EP)
H01L 2924/0002 + **H01L 2924/00**

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